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# LM48311 Boomer<sup>™</sup> Audio Power Amplifier Series Ultra-Low EMI, Filterless, 2.6W, Mono, Class D Audio Power Amplifier with E<sup>2</sup>S

Check for Samples: LM48311

#### **FEATURES**

- Passes FCC Class B Radiated Emissions with 20 Inches of Cable
- E<sup>2</sup>S System Reduces EMI while Preserving Audio Quality and Efficiency
- Output Short Circuit Protection with Auto-Recovery
- No output Filter Required
- Internally Configured Gain (6dB)
- Low power Shutdown Mode
- Minimum External Components
- "Click and Pop" Suppression
- Micro-Power Shutdown
- Available in Space-Saving DSBGA Package

#### **APPLICATIONS**

- Mobile Phones
- PDAs
- Laptops

#### **KEY SPECIFICATIONS**

- Efficiency at 3.6V, 400mW into 8Ω 85% (Typ)
- Efficiency at 5V, 1W into 8Ω 88% (Typ)
- Quiescent Power Supply Current at 5V 3.1mA
- Power Output at  $V_{DD} = 5V$ ,  $R_L = 4\Omega$ 
  - THD+N ≤ 10% 2.6W (Typ)
  - THD+N ≤ 1% 2.1W (Typ)
- Power Output at V<sub>DD</sub> = 5V, R<sub>L</sub> = 8Ω
  - THD+N ≤ 10% 1.6W (Typ)
  - THD+N ≤ 1% 1.3W (Typ)
- Shutdown Current 0.01µA (Typ)

#### DESCRIPTION

The LM48311 is a single supply, high efficiency, mono, 2.6W, filterless switching audio amplifier. The LM48311 features Texas Instruments' Enhanced Emissions Suppression (E<sup>2</sup>S) system, that features a unique patent-pending ultra low EMI, spread spectrum, PWM architecture, that significantly reduces RF emissions while preserving audio quality and efficiency. The E<sup>2</sup>S system improves battery life, reduces external component count, board area consumption, system cost, and simplifying design.

The LM48311 is designed to meet the demands of portable multimedia devices. Operating from a single 5V supply, the device is capable of delivering 2.6W of continuous output power to a  $4\Omega$  load with less than 10% THD+N. Flexible power supply requirements allow operation from 2.4V to 5.5V. The LM48311 features both a spread spectrum modulation scheme, and an advanced, patented edge rate control (ERC) architecture that significantly reduces emissions, while maintaining high quality audio reproduction (THD+N = 0.03%) and high efficiency ( $\eta$  = 88%).

The LM48311 features high efficiency compared to conventional Class AB amplifiers, and other low EMI Class D amplifiers. When driving and  $8\Omega$  speaker from a 5V supply, the device operates with 88% efficiency at  $P_{\rm O}$  = 1W. The gain of the LM48311 is internally set to 6dB, further reducing external component count. A low power shutdown mode reduces supply current consumption to  $0.01\mu A$ .

Advanced output short circuit protection with autorecovery prevents the device from being damaged during fault conditions. Superior click and pop suppression eliminates audible transients on power-up/down and during shutdown.

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# **Typical Application**

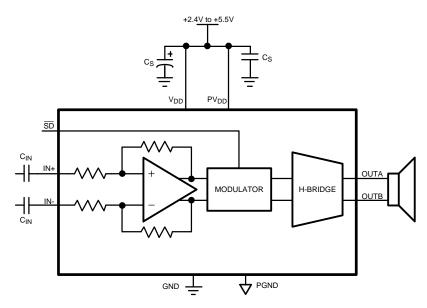


Figure 1. Typical Audio Amplifier Application Circuit

# **Connection Diagram**

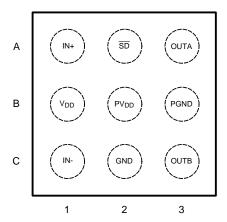


Figure 2. DSBGA Package 1.539mm x 1.565mm x 0.6mmTop View See Package Number YZR0009

### **PIN DESCRIPTIONS - BUMP DESCRIPTION**

Pin	Name	Description			
A1	IN+	Non-Inverting Input			
A2	SD	Active Low Shutdown Input. Connect to V <sub>DD</sub> for normal operation.			
А3	OUTA	Non-Inverting Output			
B1	V <sub>DD</sub>	Power Supply			
B2	$PV_{DD}$	H-Bridge Power Supply			
В3	PGND	Power Ground			
C1	IN-	Inverting Input			
C2	GND	Ground			
C3	OUTB	Inverting Output			





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# Absolute Maximum Ratings (1)(2)(3)

Supply Voltage		6.0V			
Storage Temperature		-65°C to +150°C			
Input Voltage		- 0.3V to V <sub>DD</sub> +0.3V			
Power Dissipation (4)	Internally Limited				
ESD Rating <sup>(5)</sup>	2000V				
ESD Rating <sup>(6)</sup>		200V			
Junction Temperature	Ÿ				
Thermal Resistance	$\theta_{JA}$	70°C/W			
Soldering Information See AN-1112 (SNVA00	9) "DSBGA Wafer Level Chip Sc	ale Package."			

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditionsindicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
- (2) The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.
- (3) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (4) The maximum power dissipation must be derated at elevated temperatures and is dictated by T<sub>JMAX</sub>, θ<sub>JA</sub>, and the ambient temperature, T<sub>A</sub>. The maximum allowable power dissipation is P<sub>DMAX</sub> = (T<sub>JMAX</sub>- T<sub>A</sub>) / θ<sub>JA</sub> or the number given in *Absolute Maximum Ratings*, whichever is lower.
- (5) Human body model, applicable std. JESD22-A114C.
- (6) Machine model, applicable std. JESD22-A115-A.

# Operating Ratings<sup>(1)(2)</sup>

Temperature Range	$T_{MIN} \le T_A \le T_{MAX}$	-40°C ≤ T <sub>A</sub> ≤ +85°C
	Supply Voltage (V <sub>DD</sub> , PV <sub>DD</sub> )	$2.4V \le V_{DD} \le 5.5V$

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditionsindicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
- (2) The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.



# Electrical Characteristics $V_{DD} = PV_{DD} = 5V^{(1)}$ (2)

The following specifications apply for  $A_V = 6dB$ ,  $R_L = 8\Omega$ , f = 1kHz, unless otherwise specified. Limits apply for  $T_A = 25$ °C.

				Heite		
Symbol	Parameter	Conditions	Min (3)	<b>Typ</b> (4)	Max (3)	Units (Limits)
$V_{DD}$	Supply Voltage Range	V <sub>IN</sub> = 0	2.4		5.5	V
I <sub>DD</sub>	Quiescent Power Supply Current	$V_{IN} = 0, R_L = \infty$ $V_{DD} = 3.6V$ $V_{DD} = 5V$		2.7 3.1	3.4 3.9	mA mA
I <sub>SD</sub>	Shutdown Current	Shutdown enabled		0.01	1.0	μA
Vos	Differential Output Offset Voltage	V <sub>IN</sub> = 0	-3	1	3	mV
V <sub>IH</sub>	Logic Input High Voltage		1.4			V
V <sub>IL</sub>	Logic Input Low Voltage				0.4	V
CMVR	Common Mode Input Voltage Range		0		V <sub>DD</sub> -0.25	V
T <sub>WU</sub>	Wake Up Time			7.5		ms
f <sub>SW</sub>	Switching Frequency	SYNC_IN = V <sub>DD</sub> (Spread Spectrum)		300±30		kHz
A <sub>V</sub>	Gain		5	6	7	dB
R <sub>IN</sub>	Input Resistance		17	20		kΩ
R <sub>SD</sub>	Input Resistance (SD)	SD to GND		300		kΩ
P <sub>o</sub>	Output Power	$\begin{split} R_L &= 4\Omega,  \text{THD} = 10\% \\ f &= 1 \text{kHz},  22 \text{kHz}  \text{BW} \\ V_{DD} &= 5 \text{V} \\ V_{DD} &= 3.6 \text{V} \\ V_{DD} &= 2.5 \text{V} \\ \end{split}$ $R_L &= 8\Omega,  \text{THD} = 10\% \\ f &= 1 \text{kHz},  22 \text{kHz}  \text{BW} \\ V_{DD} &= 5 \text{V} \\ V_{DD} &= 3.6 \text{V} \\ V_{DD} &= 2.5 \text{V} \\ \end{split}$ $R_L &= 4\Omega,  \text{THD} = 1\% \\ f &= 1 \text{kHz},  22 \text{kHz}  \text{BW} \\ V_{DD} &= 5 \text{V} \\ V_{DD} &= 3.6 \text{V} \\ V_{DD} &= 3.6 \text{V} \\ V_{DD} &= 2.5 \text{V} \\ \end{split}$		2.6 1.3 555 1.6 800 354 2.1 1 446		W W MW MW W W W W MW
		$R_{L} = 8\Omega, THD = 1\%$ f = 1kHz, 22kHz BW $V_{DD} = 5V$ $V_{DD} = 3.6V$ $V_{DD} = 2.5V$	1.1	1.3 640 286		W (min) mW mW
THD+N	Total Harmonic Distortion + Noise	$P_O = 200$ mW, $R_L = 8\Omega$ , $f = 1$ kHz		0.03		%
		$P_O = 100$ mW, $R_L = 8\Omega$ , $f = 1$ kHz		0.03		%
PSRR	Power Supply Rejection Ratio (Input Referred)	$V_{RIPPLE} = 200 \text{mV}_{P.P} \text{ Sine,}$ Inputs AC GND, $C_{IN} = 1 \mu \text{F}$ $f_{RIPPLE} = 217 \text{Hz}$ $f_{RIPPLE} = 1 \text{kHz}$		78 76		dB dB
CMRR	Common Mode Rejection Ratio (Input Referred)	$V_{RIPPLE} = 1V_{P-P}$ $f_{RIPPLE} = 217Hz$		86		dB
η	Efficiency	$V_{DD} = 5V$ , $P_{OUT} = 1W$ $V_{DD} = 3.6V$ , $P_{OUT} = 400$ mW		88 85		% %
SNR	Signal to Noise Ratio	P <sub>O</sub> = 1W		97		dB

<sup>(1)</sup> The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.

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<sup>(2)</sup>  $R_L$  is a resistive load in series with two inductors to simulate an actual speaker load. For  $R_L = 8\Omega$ , the load is  $15\mu H + 8\Omega$ ,  $+15\mu H$ . For  $R_L = 4\Omega$ , the load is  $15\mu H + 4\Omega + 15\mu H$ .

<sup>(3)</sup> Datasheet min/max specification limits are ensured by test or statistical analysis.

<sup>(4)</sup> Typical values represent most likely parametric norms at T<sub>A</sub> = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not ensured.



# Electrical Characteristics $V_{DD} = PV_{DD} = 5V^{(1)}$ (continued)

The following specifications apply for  $A_V = 6dB$ ,  $R_L = 8\Omega$ , f = 1kHz, unless otherwise specified. Limits apply for  $T_A = 25$ °C.

Symbol				Unita		
Symbol	Parameter	Conditions	Min (3)	<b>Typ</b> (4)	Max (3)	Units (Limits)
ε <sub>OS</sub>	Output Noise (Input Referred)	Un-weighted A-weighted		28 22		μV μV

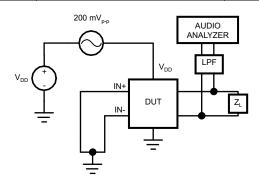


Figure 3. PSRR Test Circuit

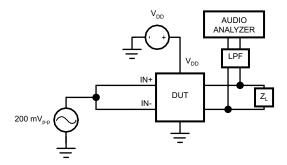


Figure 4. CMRR Test Circuit



### **Typical Performance Characteristics**

For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

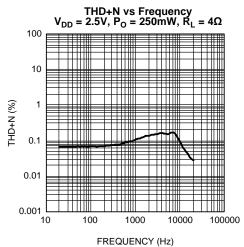
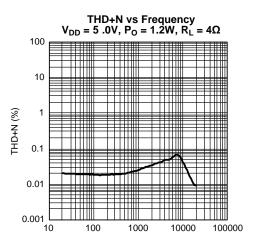
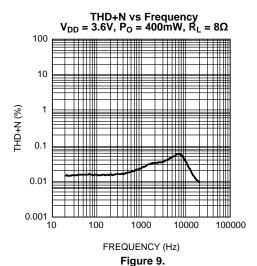


Figure 5.



FREQUENCY (Hz) Figure 7.



THD+N vs Frequency = 3.6V,  $P_0$  = 600mW,  $R_L$  = 4 $\Omega$ 100 10 (%) N+QH1 0.1 0.01 0.001 . 10 100 100000 1000 10000

FREQUENCY (Hz)

Figure 6.

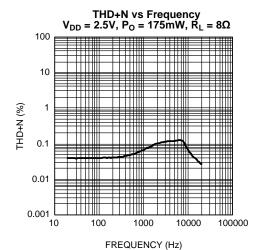


Figure 8.

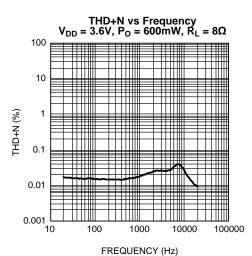


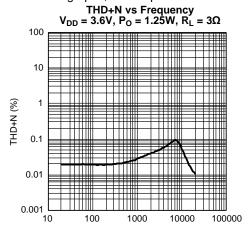
Figure 10.

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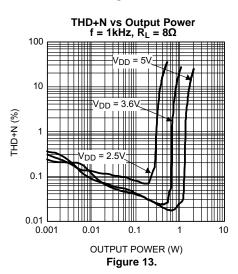
# **Typical Performance Characteristics (continued)**

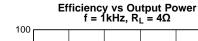
For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.



FREQUENCY (Hz)

Figure 11.





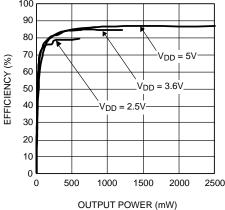


Figure 15.

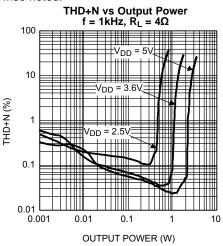


Figure 12.

# THD+N vs Output Power

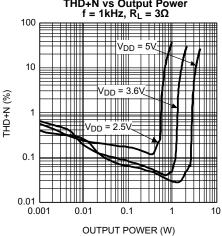


Figure 14.

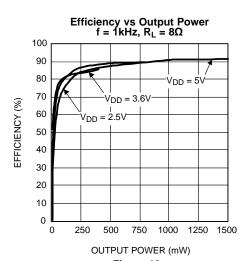
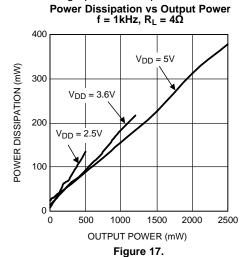


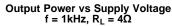
Figure 16.

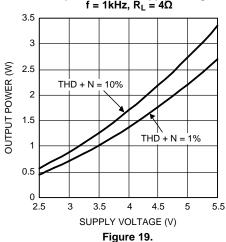


# **Typical Performance Characteristics (continued)**

For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.







CMRR vs Frequency  $V_{DD}\text{=}~5.0V,\,V_{RIPPLE}\text{=}~1V_{P\text{-}P},\,R_{L}\text{=}~8\Omega$ 

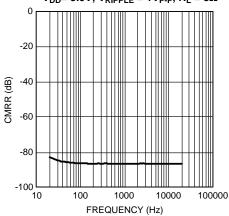


Figure 21.

# Power Dissipation vs Output Power $f = 1kHz, R_L = 8\Omega$

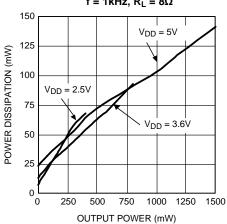


Figure 18.

# Output Power vs Supply Voltage $f = 1 kHz, \, R_L = 8 \Omega$

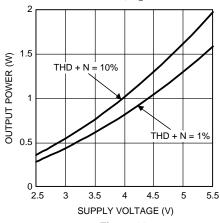


Figure 20.

 $\begin{array}{c} \text{PSRR vs Frequency} \\ \text{V}_{\text{DD}}\text{= 5.0V, V}_{\text{RIPPLE}} = 200\text{mV}_{\text{P-P}}, \, \text{R}_{\text{L}} = 8\Omega \end{array}$ 

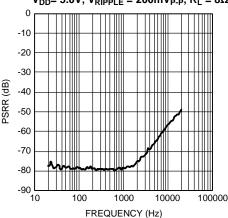


Figure 22.



### **Typical Performance Characteristics (continued)**

For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

Spread Spectrum Output Spectrum vs Frequency  $V_{DD}$ = 5.0V,  $V_{IN}$  = 1 $V_{RMS}$ ,  $R_L$  = 8 $\Omega$ 

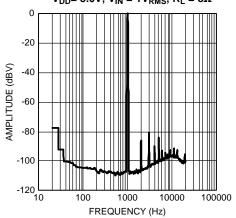


Figure 23.

# Supply Current vs Supply Voltage No Load

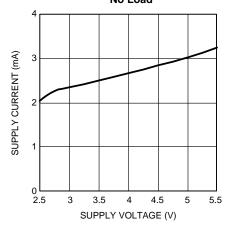


Figure 25.

# Wideband Spread Spectrum Output Spectrum vs Frequency $V_{DD} {=}~5.0V,\,R_L = 8\Omega$

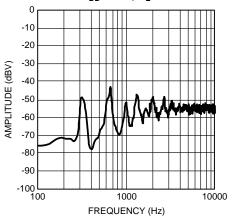


Figure 24.

# Shutdown Supply Current vs Supply Voltage No Load

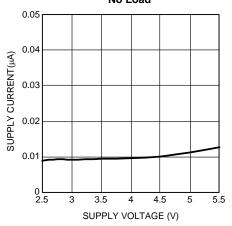


Figure 26.



#### **APPLICATION INFORMATION**

#### **GENERAL AMPLIFIER FUNCTION**

The LM48311 mono Class D audio power amplifier features a filterless modulation scheme that reduces external component count, conserving board space and reducing system cost. The outputs of the device transition from  $V_{DD}$  to GND with a 300kHz switching frequency. With no signal applied, the outputs ( $V_{OUTA}$  and  $V_{OUTB}$ ) switch with a 50% duty cycle, in phase, causing the two outputs to cancel. This cancellation results in no net voltage across the speaker, thus there is no current to the load in the idle state.

With the input signal applied, the duty cycle (pulse width) of the LM48311 outputs changes. For increasing output voltage, the duty cycle of  $V_{OUTA}$  increases, while the duty cycle of  $V_{OUTB}$  decreases. For decreasing output voltages, the converse occurs. The difference between the two pulse widths yields the differential output voltage.

# ENHANCED EMISSIONS SUPPRESSION SYSTEM (E<sup>2</sup>S)

The LM48311 features Texas Instruments' patent-pending  $E^2S$  system that reduces EMI, while maintaining high quality audio reproduction and efficiency. The  $E^2S$  system features spread spectrum and advanced edge rate control (ERC). The LM48311 ERC greatly reduces the high frequency components of the output square waves by controlling the output rise and fall times, slowing the transitions to reduce RF emissions, while maximizing THD+N and efficiency performance. The overall result of the  $E^2S$  system is a filterless Class D amplifier that passes FCC Class B radiated emissions standards with 20in of twisted pair cable, with excellent 0.03% THD+N and high 88% efficiency.

#### **SPREAD SPECTRUM**

The spread spectrum modulation reduces the need for output filters, ferrite beads or chokes. The switching frequency varies randomly by 30% about a 300kHz center frequency, reducing the wideband spectral contend, improving EMI emissions radiated by the speaker and associated cables and traces. Where a fixed frequency class D exhibits large amounts of spectral energy at multiples of the switching frequency, the spread spectrum architecture of the LM48311 spreads that energy over a larger bandwidth (See *Typical Performance Characteristics*). The cycle-to-cycle variation of the switching period does not affect the audio reproduction, efficiency, or PSRR.

#### DIFFERENTIAL AMPLIFIER EXPLANATION

As logic supplies continue to shrink, system designers are increasingly turning to differential analog signal handling to preserve signal to noise ratios with restricted voltage signs. The LM48311 features a fully differential speaker amplifier. A differential amplifier amplifies the difference between the two input signals. Traditional audio power amplifiers have typically offered only single-ended inputs resulting in a 6dB reduction of SNR relative to differential inputs. The LM48311 also offers the possibility of DC input coupling which eliminates the input coupling capacitors. A major benefit of the fully differential amplifier is the improved common mode rejection ratio (CMRR) over single ended input amplifiers. The increased CMRR of the differential amplifier reduces sensitivity to ground offset related noise injection, especially

#### POWER DISSIPATION AND EFFICIENCY

The major benefit of a Class D amplifier is increased efficiency versus a Class AB. The efficiency of the LM48311 is attributed to the region of operation of the transistors in the output stage. The Class D output stage acts as current steering switches, consuming negligible amounts of power compared to their Class AB counterparts. Most of the power loss associated with the output stage is due to the IR loss of the MOSFET onresistance, along with switching losses due to gate charge.

#### SHUTDOWN FUNCTION

The LM48311 features a low current shutdown mode. Set  $\overline{SD} = GND$  to disable the amplifier and reduce supply current to  $0.01\mu A$ .

Switch  $\overline{SD}$  between GND and  $V_{DD}$  for minimum current consumption is shutdown. The LM48311 may be disabled with shutdown voltages in between GND and  $V_{DD}$ , the idle current will be greater than the typical 0.1µA value. Increased THD+N may also be observed when a voltage of less than  $V_{DD}$  is applied to  $\overline{SD}$ .



The LM48311 shutdown input has and internal pulldown resistor. The purpose of this resistor is to eliminate any unwanted state changes when SD is floating. To minimize shutdown current, SD should be driven to GND or left floating. If SD is not driven to GND or floating, an increase in shutdown supply current will be noticed.

#### **AUDIO AMPLIFIER POWER SUPPLY BYPASSING/FILTERING**

Proper power supply bypassing is critical for low noise performance and high PSRR. Place the supply bypass capacitors as close to the device as possible. Typical applications employ a voltage regulator with 10µF and 0.1µF bypass capacitors that increase supply stability. These capacitors do not eliminate the need for bypassing of the LM48311 supply pins. A 1µF capacitor is recommended.

#### **AUDIO AMPLIFIER INPUT CAPACITOR SELECTION**

Input capacitors may be required for some applications, or when the audio source is single-ended. Input capacitors block the DC component of the audio signal, eliminating any conflict between the DC component of the audio source and the bias voltage of the LM48311. The input capacitors create a high-pass filter with the input resistors  $R_{IN}$ . The -3dB point of the high pass filter is found using Equation (1) below.

$$f = 1 / 2\pi R_{IN} C_{IN}$$
 (1)

Where R<sub>IN</sub> is the value of the input resistor given in the *Electrical Characteristics* table.

The input capacitors can also be used to remove low frequency content from the audio signal. Small speakers cannot reproduce, and may even be damaged by low frequencies. High pass filtering the audio signal helps protect the speakers. When the LM48311 is using a single-ended source, power supply noise on the ground is seen as an input signal. Setting the high-pass filter point above the power supply noise frequencies, 217Hz in a GSM phone, for example, filters out the noise such that it is not amplified and heard on the output. Capacitors with a tolerance of 10% or better are recommended for impedance matching and improved CMRR and PSRR.

#### **AUDIO AMPLIFIER GAIN**

The gain of the LM48311 is internally set to 6dB. The gain can be reduced by adding additional input resistance (LM48311 Demo Board Schematic). In this configuration, the gain of the device is given by:

$$A_V = 2 \times [R_F / (R_{INEXT} + R_{IN})]$$
 (2)

Where  $R_F$  is  $40k\Omega$ ,  $R_{IN}$  is  $20k\Omega$ , and  $R_{INEXT}$  is the value of the additional external resistor.

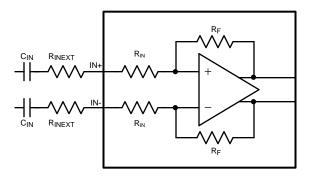


Figure 27. Reduced Gain Configuration

#### SINGLE-ENDED AUDIO AMPLIFIER CONFIGURATION

The LM48311 is compatible with single-ended sources. When configured for single-ended inputs, input capacitors must be used to block and DC component at the input of the device. Figure 28 shows the typical single-ended applications circuit.



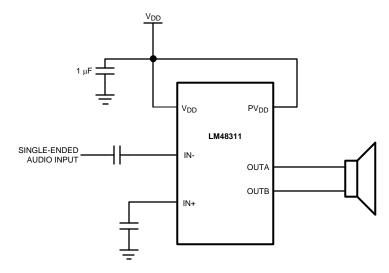


Figure 28. Single-Ended Input Configuration

#### **PCB LAYOUT GUIDELINES**

As output power increases, interconnect resistance (PCB traces and wires) between the amplifier, load and power supply create a voltage drop. The voltage loss due to the traces between the LM48311 and the load results in lower output power and decreased efficiency. Higher trace resistance between the supply and the LM48311 has the same effect as a poorly regulated supply, increasing ripple on the supply line, and reducing peak output power. The effects of residual trace resistance increases as output current increases due to higher output power, decreased load impedance or both. To maintain the highest output voltage swing and corresponding peak output power, the PCB traces that connect the output pins to the load and the supply pins to the power supply should be as wide as possible to minimize trace resistance.

The use of power and ground planes will give the best THD+N performance. In addition to reducing trace resistance, the use of power planes creates parasitic capacitors that help to filter the power supply line.

The inductive nature of the transducer load can also result in overshoot on one of both edges, clamped by the parasitic diodes to GND and  $V_{DD}$  in each case. From an EMI standpoint, this is an aggressive waveform that can radiate or conduct to other components in the system and cause interference. In is essential to keep the power and output traces short and well shielded if possible. Use of ground planes beads and micros-strip layout techniques are all useful in preventing unwanted interference.

wires or traces acting as antennas become more efficient with length. Ferrite chip inductors places close to the LM48311 outputs may be needed to reduce EMI radiation.

#### **BUILD OF MATERIALS**

Table 1. LM48311TL Demoboard Bill of Materials

Designator	Quantity	Description
C1	1	10μF ±10% 16V Tantalum Capacitor (B Case) AVX TPSB106K016R0800
C2	1	1μF ±10% 16V X5R Ceramic Capacitor (603) Panasonic ECJ-1VB1C105K
C3, C4	2	1μF ±10% 16V X7R Ceramic Capacitor (1206) Panasonic ECJ-3YB1C105K
JU1	1	3-Pin Header
LM48311TL	1	LM48311TL (9-Bump DSBGA)



# LM48311 Demo Board Schematic

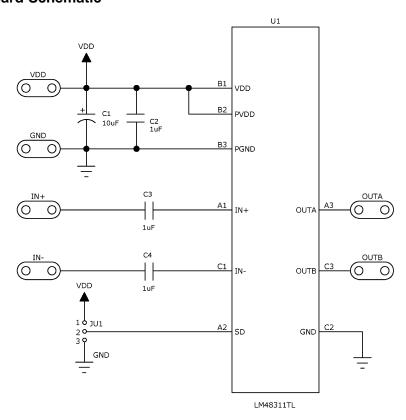


Figure 29. LM48311 Demo Board Schematic



### **Demo Boards**

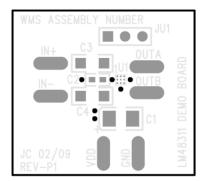


Figure 30. Top Silkscreen

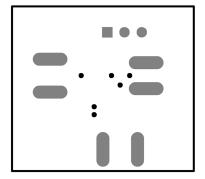


Figure 32. Bottom Silkscreen

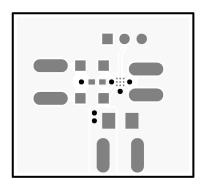


Figure 31. Top Layer

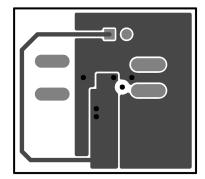


Figure 33. Bottom Layer



# **REVISION HISTORY**

Rev	Date	Description
1.0	06/25/09	Initial released.
1.01	03/17/10	Text edits (under ENHANCED EMISSIONS)

Changes from Revision A (May 2013) to Revision B						
•	Changed layout of National Data Sheet to TI format	1	14			



# PACKAGE OPTION ADDENDUM

10-Dec-2020

#### PACKAGING INFORMATION

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM48311TL/NOPB	ACTIVE	DSBGA	YZR	9	250	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G N1	Samples
LM48311TLX/NOPB	ACTIVE	DSBGA	YZR	9	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G N1	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

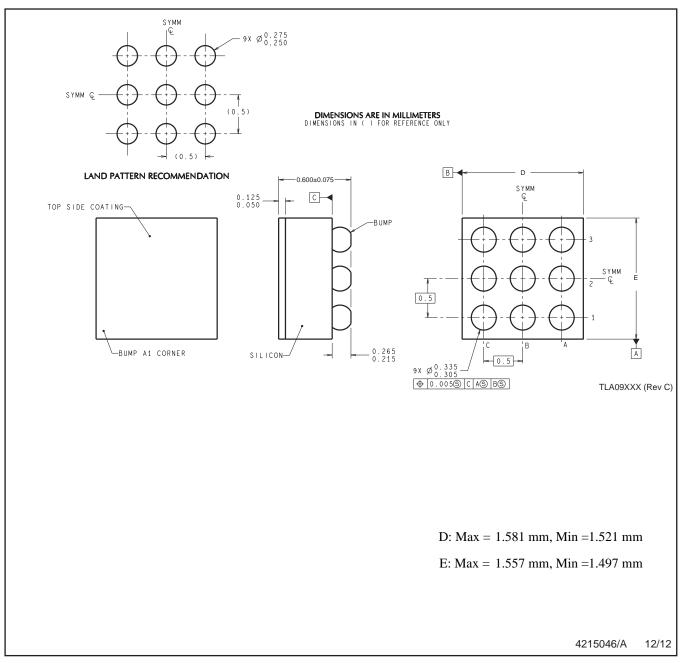
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM48311TL/NOPB	DSBGA	YZR	9	250	178.0	8.4	1.7	1.7	0.76	4.0	8.0	Q1
LM48311TLX/NOPB	DSBGA	YZR	9	3000	178.0	8.4	1.7	1.7	0.76	4.0	8.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	ge Type Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)
LM48311TL/NOPB	DSBGA	YZR	9	250	208.0	191.0	35.0
LM48311TLX/NOPB	DSBGA	YZR	9	3000	208.0	191.0	35.0



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

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